

LASER MICROMACHINING SAPPHIRE

Sapphire Application

Material

Sapphire

Feature Size

0.25mm deep

1mm wide trench

3 mm diameter circle

Laser Type

Picosecond Solid-State Laser

Industry Applications

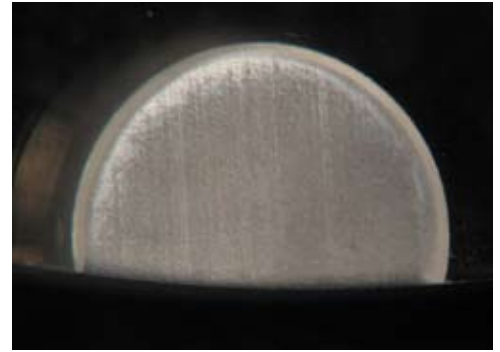
Microelectronics

Optics

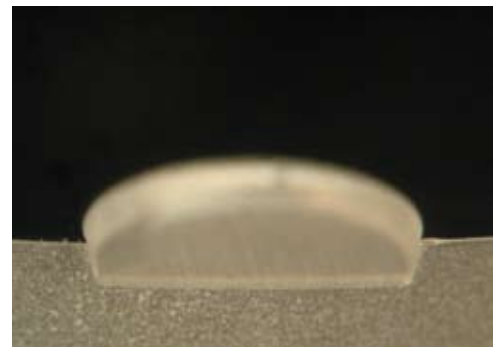
Microfluidics

Application Description

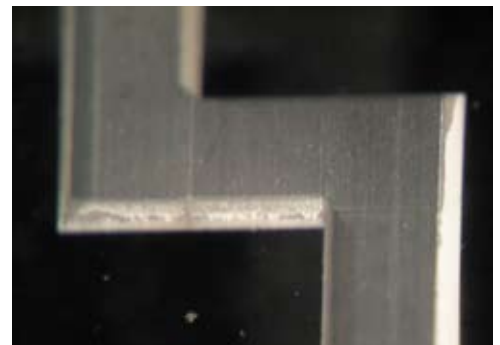
Picosecond laser micromachining enables transparent materials like sapphire to be ablated.



3mm diameter circle with 0.25mm depth



Side view of 3mm diameter circle with a depth of 0.25mm



1mm wide trench machined 0.25mm deep

Mound Laser & Photonics Center, Inc.
965 Capstone Dr., Suite 308
P.O. Box 223
Miamisburg, Ohio 45342

MI DC
IVILT Inc. 
Mound Laser & Photonics Center

(P) 937-865-4070
(F) 937-865-3680
sales@mlpc.com
www.mlpc.com